Renesas Electronics America Inc - R5F10WLEAFB#50 Datasheet

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	RL78
Core Size	16-Bit
Speed	24MHz
Connectivity	CSI, I²C, LINbus, UART/USART
Peripherals	DMA, LCD, LVD, POR, PWM, WDT
Number of I/O	42
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	1.6V ~ 5.5V
Data Converters	A/D 9x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LFQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f10wleafb-50

Pin Count	Package	Data Flash	Fields of Application[Note]	Ordering Part Number
64 pins	64-pin plastic LQFP (12 × 12 mm, 0.65 mm pitch)	Mounted	A	R5F10WLAAFA#30, R5F10WLAAFA#50, R5F10WLCAFA#30, R5F10WLCAFA#50, R5F10WLDAFA#30, R5F10WLDAFA#50, R5F10WLEAFA#30, R5F10WLEAFA#50, R5F10WLFAFA#30, R5F10WLFAFA#50, R5F10WLGAFA#30, R5F10WLGAFA#50
	64-pin plastic LFQFP (10 × 10 mm, 0.5 mm pitch)	Mounted	A G	R5F10WLAAFB#30, R5F10WLAAFB#50, R5F10WLCAFB#30, R5F10WLCAFB#50, R5F10WLDAFB#30, R5F10WLDAFB#50, R5F10WLEAFB#30, R5F10WLEAFB#50, R5F10WLFAFB#30, R5F10WLFAFB#50, R5F10WLGAFB#30, R5F10WLGAFB#50, R5F10WLAGFB#30, R5F10WLAGFB#50, R5F10WLCGFB#30, R5F10WLCGFB#50, R5F10WLDGFB#30, R5F10WLDGFB#50, R5F10WLEGFB#30, R5F10WLEGFB#50, R5F10WLFGFB#30, R5F10WLFGFB#50, R5F10WLGGFB#30, R5F10WLGGFB#50
80 pins	80-pin plastic LQFP (14 × 14 mm, 0.65 mm pitch)	Mounted	A	R5F10WMAAFA#30, R5F10WMAAFA#50, R5F10WMCAFA#30, R5F10WMCAFA#50, R5F10WMDAFA#30, R5F10WMDAFA#50, R5F10WMEAFA#30, R5F10WMEAFA#50, R5F10WMFAFA#30, R5F10WMFAFA#50, R5F10WMGAFA#30, R5F10WMGAFA#50
	80-pin plastic LFQFP (12 × 12 mm, 0.5 mm pitch)	Mounted	A G	R5F10WMAAFB#30, R5F10WMAAFB#50, R5F10WMCAFB#30, R5F10WMCAFB#50, R5F10WMDAFB#30, R5F10WMDAFB#50, R5F10WMEAFB#30, R5F10WMEAFB#50, R5F10WMFAFB#30, R5F10WMFAFB#50, R5F10WMGAFB#30, R5F10WMGAFB#50, R5F10WMAGFB#30, R5F10WMAGFB#50, R5F10WMCGFB#30, R5F10WMCGFB#50, R5F10WMDGFB#30, R5F10WMDGFB#50, R5F10WMEGFB#30, R5F10WMEGFB#50, R5F10WMFGFB#30, R5F10WMFGFB#50, R5F10WMGGFB#30, R5F10WMGGFB#50

Note For the fields of application, see **Figure 1-1 Part Number, Memory Size, and Package of RL78/L13.**

Caution The ordering part numbers represent the numbers at the time of publication. For the latest ordering part numbers, refer to the target product page of the Renesas Electronics website.

1.4 Pin Identification

ANI0, ANI1, ANI16 to ANI25: Analog Input
AV_{REFM}: Analog Reference Voltage Minus
AV_{REFP}: Analog Reference Voltage Plus
CAPH, CAPL: Capacitor for LCD
COM0 to COM7: LCD Common Output
EXCLK: External Clock Input (Main System Clock)
EXCLKS: External Clock Input (Subsystem Clock)
INTP0 to INTP7: External Interrupt Input
IVCMP0, IVCMP1: Comparator Input
IVREF0, IVREF1: Comparator Reference Input
KR0 to KR7: Key Return
P00 to P07: Port 0
P10 to P17: Port 1
P20 to P27: Port 2
P30 to P35: Port 3
P40 to P47: Port 4
P50 to P57: Port 5
P60, P61: Port 6
P70 to P77: Port 7
P121 to P127: Port 12
P130, P137: Port 13
PCLBUZ0, PCLBUZ1: Programmable Clock Output/ Buzzer Output
REGC: Regulator Capacitance
REMOOUT: Remote control Output
$\overline{\text{RESET}}$: Reset
RTC1HZ: Real-time Clock 2 Correction Clock (1 Hz) Output
RxD0 to RxD3: Receive Data
SCK00, SCK10, SCLA0: Serial Clock Input/Output
SCL00, SCL10: Serial Clock Output
SDAA0, SDA00, SDA10: Serial Data Input/Output
SEG0 to SEG50: LCD Segment Output
SI00, SI10: Serial Data Input
SO00, SO10: Serial Data Output
TI00 to TI07: Timer Input
TO00 to TO07, TKBO00, TKBO01-0, TKBO01-1, TKBO01-2: Timer Output
TOOL0: Data Input/Output for Tool
TOOLRxD, TOOLTxD: Data Input/Output for External Device
TxD0 to TxD3: Transmit Data
VCOUT0, VCOUT1: Comparator Output
V_{DD}: Power Supply
V_{L1} to V_{L4}: LCD Power Supply
V_{SS}: Ground
X1, X2: Crystal Oscillator (Main System Clock)
XT1, XT2: Crystal Oscillator (Subsystem Clock)

2. ELECTRICAL SPECIFICATIONS (T_A = –40 to +85°C)

Target products A: Consumer applications; T_A = –40 to +85°C

R5F10WLAAFA, R5F10WLCAFA, R5F10WLDAFA,
R5F10WLEAFA, R5F10WLFAFA, R5F10WLGAFA,
R5F10WLAAFB, R5F10WLCAFB, R5F10WLDAFB,
R5F10WLEAFB, R5F10WLFAFB, R5F10WLGAFB,
R5F10WMAAFA, R5F10WMCAFA, R5F10WMDAFA,
R5F10WMEAFA, R5F10WMFAFA, R5F10WMGAFA,
R5F10WMAAFB, R5F10WMCAFB, R5F10WMDAFB,
R5F10WMEAFB, R5F10WMFAFB, R5F10WMGAFB

G: Industrial applications; when using T_A = –40 to +105°C specification products at T_A = –40 to +85°C

R5F10WLAGFB, R5F10WLCGFB, R5F10WLDGFB,
R5F10WLEGFB, R5F10WLFGFB, R5F10WLGGFB
R5F10WMAGFB, R5F10WMCGFB, R5F10WMDGFB,
R5F10WMEGFB, R5F10WMFGFB, R5F10WMGGFB

Cautions 1. The RL78 microcontrollers have an on-chip debug function, which is provided for development and evaluation. Do not use the on-chip debug function in products designated for mass production, because the guaranteed number of rewritable times of the flash memory may be exceeded when this function is used, and product reliability therefore cannot be guaranteed. Renesas Electronics is not liable for problems occurring when the on-chip debug function is used.

2. The pins mounted depend on the product. See 2.1 Port Function to 2.2.1 With functions for each product in the RL78/L13 User's Manual.

Absolute Maximum Ratings (2/3)

Parameter	Symbol	Conditions		Ratings	Unit
LCD voltage	V_{L1}	V_{L1} voltage[Note 1]		–0.3 to +2.8 and –0.3 to V_{L4} +0.3	V
	V_{L2}	V_{L2} voltage[Note 1]		–0.3 to V_{L4} +0.3[Note 2]	V
	V_{L3}	V_{L3} voltage[Note 1]		–0.3 to V_{L4} +0.3[Note 2]	V
	V_{L4}	V_{L4} voltage[Note 1]		–0.3 to +6.5	V
	V_{LCAP}	CAPL, CAPH voltage[Note 1]		–0.3 to V_{L4} +0.3[Note 2]	V
	V_{OUT}	COM0 to COM7 SEG0 to SEG50 output voltage	External resistance division method	–0.3 to V_{DD} +0.3[Note 2]	V
			Capacitor split method	–0.3 to V_{DD} +0.3[Note 2]	V
			Internal voltage boosting method	–0.3 to V_{L4} +0.3[Note 2]	V

Notes 1. This value only indicates the absolute maximum ratings when applying voltage to the V_{L1}, V_{L2}, V_{L3}, and V_{L4} pins; it does not mean that applying voltage to these pins is recommended. When using the internal voltage boosting method or capacitance split method, connect these pins to V_{SS} via a capacitor (0.47 μF ± 30%) and connect a capacitor (0.47 μF ± 30%) between the CAPL and CAPH pins.

2. Must be 6.5 V or lower.

Caution Product quality may suffer if the absolute maximum rating is exceeded even momentarily for any parameter. That is, the absolute maximum ratings are rated values at which the product is on the verge of suffering physical damage, and therefore the product must be used under conditions that ensure that the absolute maximum ratings are not exceeded.

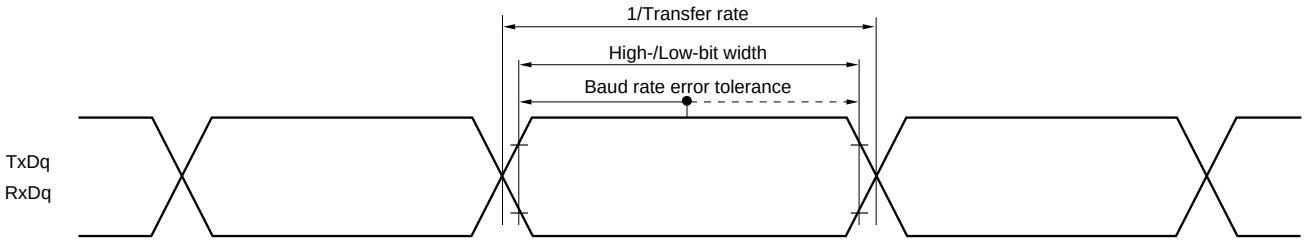
Remark V_{SS}: Reference voltage

(T_A = –40 to +85°C, 1.6 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V) (2/2)

Parameter	Symbol	Conditions				MIN.	TYP.	MAX.	Unit
Supply current[Note 1]	I_{DD2}[Note 2]	HALT mode	HS (high-speed main) mode[Note 7]	f_{HOCO} = 48 MHz[Note 4], f_{IH} = 24 MHz[Note 4]	V_{DD} = 5.0 V		0.71	1.95	mA
					V_{DD} = 3.0 V		0.71	1.95	
				f_{HOCO} = 24 MHz[Note 4], f_{IH} = 24 MHz[Note 4]	V_{DD} = 5.0 V		0.49	1.64	mA
					V_{DD} = 3.0 V		0.49	1.64	
				f_{HOCO} = 16 MHz[Note 4], f_{IH} = 16 MHz[Note 4]	V_{DD} = 5.0 V		0.43	1.11	mA
					V_{DD} = 3.0 V		0.43	1.11	
			LS (low-speed main) mode[Note 7]	f_{HOCO} = 8 MHz[Note 4], f_{IH} = 8 MHz[Note 4]	V_{DD} = 3.0 V		280	770	μA
					V_{DD} = 2.0 V		280	770	
			LV (low-voltage main) mode[Note 7]	f_{HOCO} = 4 MHz[Note 4], f_{IH} = 4 MHz[Note 4]	V_{DD} = 3.0 V		430	700	μA
					V_{DD} = 2.0 V		430	700	
			HS (high-speed main) mode[Note 7]	f_{MX} = 20 MHz[Note 3], V_{DD} = 5.0 V	Square wave input		0.31	1.42	mA
					Resonator connection		0.48	1.42	
				f_{MX} = 20 MHz[Note 3], V_{DD} = 3.0 V	Square wave input		0.29	1.42	mA
					Resonator connection		0.48	1.42	
				f_{MX} = 16 MHz[Note 3], V_{DD} = 5.0 V	Square wave input		0.26	0.86	mA
					Resonator connection		0.45	1.15	
				f_{MX} = 16 MHz[Note 3], V_{DD} = 3.0 V	Square wave input		0.25	0.86	mA
					Resonator connection		0.44	1.15	
				f_{MX} = 10 MHz[Note 3], V_{DD} = 5.0 V	Square wave input		0.20	0.63	mA
					Resonator connection		0.28	0.71	
				f_{MX} = 10 MHz[Note 3], V_{DD} = 3.0 V	Square wave input		0.19	0.63	mA
					Resonator connection		0.28	0.71	
			LS (low-speed main) mode[Note 7]	f_{MX} = 8 MHz[Note 3], V_{DD} = 3.0 V	Square wave input		100	560	μA
					Resonator connection		160	560	
				f_{MX} = 8 MHz[Note 3], V_{DD} = 2.0 V	Square wave input		100	560	μA
					Resonator connection		160	560	
			Subsystem clock operation	f_{SUB} = 32.768 kHz[Note 5], T_A = –40°C	Square wave input		0.34	0.62	μA
					Resonator connection		0.51	0.80	
				f_{SUB} = 32.768 kHz[Note 5], T_A = +25°C	Square wave input		0.38	0.62	μA
					Resonator connection		0.57	0.80	
				f_{SUB} = 32.768 kHz[Note 5], T_A = +50°C	Square wave input		0.46	2.30	μA
					Resonator connection		0.67	2.49	
				f_{SUB} = 32.768 kHz[Note 5], T_A = +70°C	Square wave input		0.65	4.03	μA
					Resonator connection		0.91	4.22	
				f_{SUB} = 32.768 kHz[Note 5], T_A = +85°C	Square wave input		1.00	8.04	μA
					Resonator connection		1.31	8.23	
	I_{DD3}[Note 6]	STOP mode[Note 8]	T_A = –40°C				0.18	0.52	μA
			T_A = +25°C				0.24	0.52	
			T_A = +50°C				0.33	2.21	
			T_A = +70°C				0.53	3.94	
			T_A = +85°C				0.93	7.95	

(**Notes** and **Remarks** are listed on the next page.)

UART mode bit width (during communication at same potential) (reference)



Remarks 1. q: UART number (q = 0 to 3), g: PIM and POM number (g = 0, 1, 3)

2. f_{MCK}: Serial array unit operation clock frequency
(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn). m: Unit number, n: Channel number (mn = 00 to 03, 10 to 13))

(3) During communication at same potential (CSI mode) (slave mode, SCKp... external clock input)

(T_A = –40 to +85°C, 1.6 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Parameter	Symbol	Conditions		HS (high-speed main) Mode		LS (low-speed main) Mode		LV (low-voltage main) Mode		Unit
				MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
SCKp cycle time[Note 5]	t_{KCY2}	4.0 V ≤ V_{DD} ≤ 5.5 V	f_{MCK} > 20 MHz	8/f_{MCK}		–		–		ns
			f_{MCK} ≤ 20 MHz	6/f_{MCK}		6/f_{MCK}		6/f_{MCK}		ns
		2.7 V ≤ V_{DD} ≤ 5.5 V	f_{MCK} > 16 MHz	8/f_{MCK}		–		–		ns
			f_{MCK} ≤ 16 MHz	6/f_{MCK}		6/f_{MCK}		6/f_{MCK}		ns
		2.4 V ≤ V_{DD} ≤ 5.5 V		6/f_{MCK} and 500		6/f_{MCK}		6/f_{MCK}		ns
		1.8 V ≤ V_{DD} ≤ 5.5 V		–		6/f_{MCK}		6/f_{MCK}		ns
		1.6 V ≤ V_{DD} ≤ 5.5 V		–		–		6/f_{MCK}		ns
SCKp high-/low-level width	t_{KH2}, t_{KL2}	4.0 V ≤ V_{DD} ≤ 5.5 V		t_{KCY2}/2–7		t_{KCY2}/2–7		t_{KCY2}/2–7		ns
		2.7 V ≤ V_{DD} ≤ 5.5 V		t_{KCY2}/2–8		t_{KCY2}/2–8		t_{KCY2}/2–8		ns
		2.4 V ≤ V_{DD} ≤ 5.5 V		t_{KCY2}/2–18		t_{KCY2}/2–18		t_{KCY2}/2–18		ns
		1.8 V ≤ V_{DD} ≤ 5.5 V		–		t_{KCY2}/2–18		t_{KCY2}/2–18		ns
		1.6 V ≤ V_{DD} ≤ 5.5 V		–		–		t_{KCY2}/2–66		ns
SIp setup time (to SCKp↑)[Note 1]	t_{SIK2}	2.7 V ≤ V_{DD} ≤ 5.5 V		1/f_{MCK}+20		1/f_{MCK}+30		1/f_{MCK}+30		ns
		2.4 V ≤ V_{DD} ≤ 5.5 V		1/f_{MCK}+30		1/f_{MCK}+30		1/f_{MCK}+30		ns
		1.8 V ≤ V_{DD} ≤ 5.5 V		–		1/f_{MCK}+30		1/f_{MCK}+30		ns
		1.6 V ≤ V_{DD} ≤ 5.5 V		–		–		1/f_{MCK}+40		ns
SIp hold time (from SCKp↑)[Note 2]	t_{KSI2}	2.4 V ≤ V_{DD} ≤ 5.5 V		1/f_{MCK}+31		1/f_{MCK}+31		1/f_{MCK}+31		ns
		1.8 V ≤ V_{DD} ≤ 5.5 V		–		1/f_{MCK}+31		1/f_{MCK}+31		ns
		1.6 V ≤ V_{DD} ≤ 5.5 V		–		–		1/f_{MCK}+250		ns
Delay time from SCKp↓ to SOp output[Note 3]	t_{KSO2}	C = 30 pF[Note 4]	2.7 V ≤ V_{DD} ≤ 5.5 V		2/f_{MCK}+44		2/f_{MCK}+110		2/f_{MCK}+110	ns
			2.4 V ≤ V_{DD} ≤ 5.5 V		2/f_{MCK}+75		2/f_{MCK}+110		2/f_{MCK}+110	ns
			1.8 V ≤ V_{DD} ≤ 5.5 V		–		2/f_{MCK}+110		2/f_{MCK}+110	ns
			1.6 V ≤ V_{DD} ≤ 5.5 V		–		–		2/f_{MCK}+220	ns

Notes 1. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The SIp setup time becomes "to SCKp↓" when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.

2. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The SIp hold time becomes "from SCKp↓" when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.

3. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The delay time to SOp output becomes "from SCKp↑" when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.

4. C is the load capacitance of the SOp output lines.

5. Transfer rate in SNOOZE mode: MAX. 1 Mbps

Caution Select the normal input buffer for the SIp pin and SCKp pin and the normal output mode for the SOp pin by using port input mode register g (PIMg) and port output mode register g (POMg).

Remarks 1. p: CSI number (p = 00, 10), m: Unit number (m = 0), n: Channel number (n = 0, 2), g: PIM number (g = 0, 1)

2. f_{MCK}: Serial array unit operation clock frequency
(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn). m: Unit number, n: Channel number (mn = 00, 02))

(5) Communication at different potential (1.8 V, 2.5 V, 3 V) (UART mode) (2/2)

(T_A = –40 to +85°C, 1.8 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Parameter	Symbol	Conditions		HS (high-speed main) Mode		LS (low-speed main) Mode		LV (low-voltage main) Mode		Unit
				MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
Transfer rate		Trans mission	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V		**Note 1**		**Note 1**		**Note 1**	bps
			Theoretical value of the maximum transfer rate (C_b = 50 pF, R_b = 1.4 kΩ, V_b = 2.7 V)		2.8 Note 2		2.8 Note 2		2.8 Note 2	Mbps
			2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V		**Note 3**		**Note 3**		**Note 3**	bps
			Theoretical value of the maximum transfer rate (C_b = 50 pF, R_b = 2.7 kΩ, V_b = 2.3 V)		1.2 Note 4		1.2 Note 4		1.2 Note 4	Mbps
			1.8 V (2.4 V Note 8) ≤ V_{DD} < 3.3 V, 1.6 V ≤ V_b ≤ 2.0 V		**Notes 5, 6**		**Notes 5, 6**		**Notes 5, 6**	bps
			Theoretical value of the maximum transfer rate (C_b = 50 pF, R_b = 5.5 kΩ, V_b = 1.6 V)		0.43 Note 7		0.43 Note 7		0.43 Note 7	Mbps

Notes 1. The smaller maximum transfer rate derived by using f_{MCK}/6 or the following expression is the valid maximum transfer rate.

Expression for calculating the transfer rate when 4.0 V ≤ V_{DD} ≤ 5.5 V and 2.7 V ≤ V_b ≤ 4.0 V

$$\text{Maximum transfer rate} = \frac{1}{\{-C_b \times R_b \times \ln(1 - \frac{2.2}{V_b})\} \times 3} \text{ [bps]}$$

$$\text{Baud rate error (theoretical value)} = \frac{\frac{1}{\text{Transfer rate} \times 2} - \{-C_b \times R_b \times \ln(1 - \frac{2.2}{V_b})\}}{(\frac{1}{\text{Transfer rate}}) \times \text{Number of transferred bits}} \times 100 \text{ [\%]}$$

* This value is the theoretical value of the relative difference between the transmission and reception sides.

2. This value as an example is calculated when the conditions described in the “Conditions” column are met. Refer to **Note 1** above to calculate the maximum transfer rate under conditions of the customer.

3. The smaller maximum transfer rate derived by using f_{MCK}/6 or the following expression is the valid maximum transfer rate.

Expression for calculating the transfer rate when 2.7 V ≤ V_{DD} < 4.0 V and 2.3 V ≤ V_b ≤ 2.7 V

$$\text{Maximum transfer rate} = \frac{1}{\{-C_b \times R_b \times \ln(1 - \frac{2.0}{V_b})\} \times 3} \text{ [bps]}$$

$$\text{Baud rate error (theoretical value)} = \frac{\frac{1}{\text{Transfer rate} \times 2} - \{-C_b \times R_b \times \ln(1 - \frac{2.0}{V_b})\}}{(\frac{1}{\text{Transfer rate}}) \times \text{Number of transferred bits}} \times 100 \text{ [\%]}$$

* This value is the theoretical value of the relative difference between the transmission and reception sides.

4. This value as an example is calculated when the conditions described in the “Conditions” column are met. Refer to **Note 3** above to calculate the maximum transfer rate under conditions of the customer.

5. Use it with $V_{DD} \geq V_b$.

Notes 6. The smaller maximum transfer rate derived by using f_{MCK}/6 or the following expression is the valid maximum transfer rate.

Expression for calculating the transfer rate when 1.8 V (2.4 V[Note 8]) ≤ V_{DD} < 3.3 V and 1.6 V ≤ V_b ≤ 2.0 V

$$\text{Maximum transfer rate} = \frac{1}{\{-C_b \times R_b \times \ln(1 - \frac{1.5}{V_b})\} \times 3} \text{ [bps]}$$

$$\text{Baud rate error (theoretical value)} = \frac{\frac{1}{\text{Transfer rate} \times 2} - \{-C_b \times R_b \times \ln(1 - \frac{1.5}{V_b})\}}{(\frac{1}{\text{Transfer rate}}) \times \text{Number of transferred bits}} \times 100 \text{ [\%]}$$

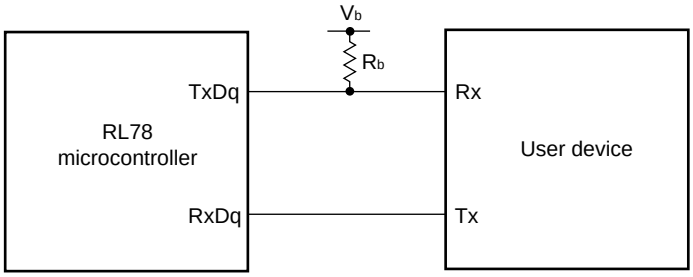
* This value is the theoretical value of the relative difference between the transmission and reception sides.

7. This value as an example is calculated when the conditions described in the “Conditions” column are met. Refer to **Note 6** above to calculate the maximum transfer rate under conditions of the customer.

8. Condition in the HS (high-speed main) mode

Caution Select the TTL input buffer for the RxDq pin and the N-ch open drain output (V_{DD} tolerance) mode for the TxDq pin by using port input mode register g (PIMg) and port output mode register g (POMg). For V_{IH} and V_{IL}, see the DC characteristics with TTL input buffer selected.

UART mode connection diagram (during communication at different potential)



Notes 1. Transfer rate in SNOOZE mode: MAX. 1 Mbps

2. Condition in HS (high-speed main) mode

3. Use it with $V_{DD} \geq V_b$.

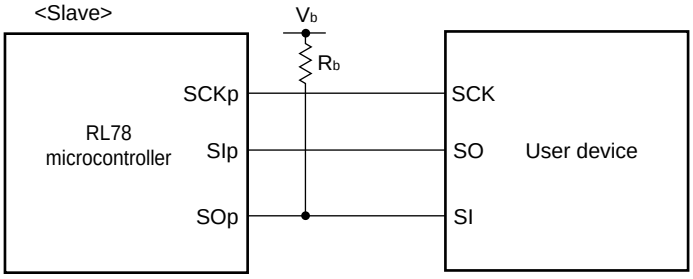
4. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The SIp setup time becomes "to SCKp↓" when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.

5. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The SIp hold time becomes "from SCKp↓" when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.

6. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The delay time to SOp output becomes "from SCKp↑" when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.

Caution Select the TTL input buffer for the SIp pin and SCKp pin and the N-ch open drain output (V_{DD} tolerance) mode for the SOp pin by using port input mode register g (PIMg) and port output mode register g (POMg). For V_{IH} and V_{IL}, see the DC characteristics with TTL input buffer selected.

CSI mode connection diagram (during communication at different potential)



2.5.2 Serial interface IICA

(1) I^2C standard mode (1/2)

(T_A = –40 to +85°C, 1.6 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Parameter	Symbol	Conditions		HS (high-speed main) Mode		LS (low-speed main) Mode		LV (low-voltage main) Mode		Unit
				MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
SCLA0 clock frequency	f_{SCL}	Normal mode: f_{CLK} ≥ 1 MHz	2.7 V ≤ V_{DD} ≤ 5.5 V	0	100	0	100	0	100	kHz
			1.8 V (2.4 V[Note 3]) ≤ V_{DD} ≤ 5.5 V	0	100	0	100	0	100	kHz
			1.6 V ≤ V_{DD} ≤ 5.5 V	–	–	–	–	0	100	kHz
Setup time of restart condition	$t_{SU:STA}$	2.7 V ≤ V_{DD} ≤ 5.5 V		4.7		4.7		4.7		μs
		1.8 V (2.4 V[Note 3]) ≤ V_{DD} ≤ 5.5 V		4.7		4.7		4.7		μs
		1.6 V ≤ V_{DD} ≤ 5.5 V		–	–	–	–	4.7		μs
Hold time[Note 1]	$t_{HD:STA}$	2.7 V ≤ V_{DD} ≤ 5.5 V		4.0		4.0		4.0		μs
		1.8 V (2.4 V[Note 3]) ≤ V_{DD} ≤ 5.5 V		4.0		4.0		4.0		μs
		1.6 V ≤ V_{DD} ≤ 5.5 V		–	–	–	–	4.0		μs
Hold time when SCLA0 = “L”	t_{LOW}	2.7 V ≤ V_{DD} ≤ 5.5 V		4.7		4.7		4.7		μs
		1.8 V (2.4 V[Note 3]) ≤ V_{DD} ≤ 5.5 V		4.7		4.7		4.7		μs
		1.6 V ≤ V_{DD} ≤ 5.5 V		–	–	–	–	4.7		μs
Hold time when SCLA0 = “H”	t_{HIGH}	2.7 V ≤ V_{DD} ≤ 5.5 V		4.0		4.0		4.0		μs
		1.8 V (2.4 V[Note 3]) ≤ V_{DD} ≤ 5.5 V		4.0		4.0		4.0		μs
		1.6 V ≤ V_{DD} ≤ 5.5 V		–	–	–	–	4.0		μs

(**Notes**, **Caution** and **Remark** are listed on the next page.)

(3) When reference voltage (+) = Internal reference voltage (ADREFP1 = 1, ADREFP0 = 0), reference voltage (–) = AVREFM/ANI1 (ADREFM = 1), target pins: ANI0, ANI16 to ANI25

(T_A = –40 to +85°C, 2.4 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V, Reference voltage (+) = V_{BGR} Note 3, Reference voltage (–) = AV_{REFM} Note 4 = 0 V, HS (high-speed main) mode)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Resolution	RES				8		bit
Conversion time	t_{CONV}	8-bit resolution	2.4 V ≤ V_{DD} ≤ 5.5 V	17		39	μs
Zero-scale error Notes 1, 2	E_{ZS}	8-bit resolution	2.4 V ≤ V_{DD} ≤ 5.5 V			±0.60	%FSR
Integral linearity error Note 1	ILE	8-bit resolution	2.4 V ≤ V_{DD} ≤ 5.5 V			±2.0	LSB
Differential linearity error Note 1	DLE	8-bit resolution	2.4 V ≤ V_{DD} ≤ 5.5 V			±1.0	LSB
Analog input voltage	V_{AIN}			0		V_{BGR} Note 3	V

Notes 1. Excludes quantization error (±1/2 LSB).

2. This value is indicated as a ratio (%FSR) to the full-scale value.

3. See **2.6.2 Temperature sensor/internal reference voltage characteristics**.

4. When reference voltage (–) = V_{SS}, the MAX. values are as follows.

Zero-scale error: Add ±0.35%FSR to the AV_{REFM} MAX. value.

Integral linearity error: Add ±0.5 LSB to the AV_{REFM} MAX. value.

Differential linearity error: Add ±0.2 LSB to the AV_{REFM} MAX. value.

2.6.2 Temperature sensor /internal reference voltage characteristics

(T_A = –40 to +85°C, 2.4 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V, HS (high-speed main) mode)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Temperature sensor output voltage	V_{TMPS25}	ADS register = 80H, T_A = +25°C		1.05		V
Internal reference output voltage	V_{BGR}	ADS register = 81H	1.38	1.45	1.5	V
Temperature coefficient	F_{VTMPS}	Temperature sensor that depends on the temperature		–3.6		mV/°C
Operation stabilization wait time	t_{AMP}				5	μs

2.6.5 LVD circuit characteristics

LVD Detection Voltage of Reset Mode and Interrupt Mode

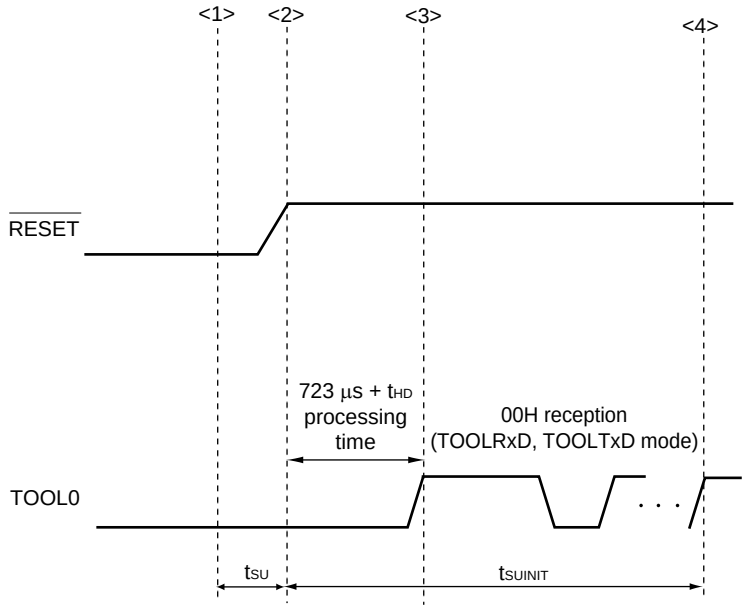
(T_A = –40 to +85°C, $V_{PDR} \leq V_{DD} \leq 5.5$ V, V_{SS} = 0 V)

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Detection voltage	Supply voltage level	V_{LVD0}	When power supply rises	3.98	4.06	4.14	V
			When power supply falls	3.90	3.98	4.06	V
		V_{LVD1}	When power supply rises	3.68	3.75	3.82	V
			When power supply falls	3.60	3.67	3.74	V
		V_{LVD2}	When power supply rises	3.07	3.13	3.19	V
			When power supply falls	3.00	3.06	3.12	V
		V_{LVD3}	When power supply rises	2.96	3.02	3.08	V
			When power supply falls	2.90	2.96	3.02	V
		V_{LVD4}	When power supply rises	2.86	2.92	2.97	V
			When power supply falls	2.80	2.86	2.91	V
		V_{LVD5}	When power supply rises	2.76	2.81	2.87	V
			When power supply falls	2.70	2.75	2.81	V
		V_{LVD6}	When power supply rises	2.66	2.71	2.76	V
			When power supply falls	2.60	2.65	2.70	V
		V_{LVD7}	When power supply rises	2.56	2.61	2.66	V
			When power supply falls	2.50	2.55	2.60	V
		V_{LVD8}	When power supply rises	2.45	2.50	2.55	V
			When power supply falls	2.40	2.45	2.50	V
		V_{LVD9}	When power supply rises	2.05	2.09	2.13	V
			When power supply falls	2.00	2.04	2.08	V
		V_{LVD10}	When power supply rises	1.94	1.98	2.02	V
			When power supply falls	1.90	1.94	1.98	V
		V_{LVD11}	When power supply rises	1.84	1.88	1.91	V
			When power supply falls	1.80	1.84	1.87	V
		V_{LVD12}	When power supply rises	1.74	1.77	1.81	V
			When power supply falls	1.70	1.73	1.77	V
		V_{LVD13}	When power supply rises	1.64	1.67	1.70	V
			When power supply falls	1.60	1.63	1.66	V
Minimum pulse width		t_{LW}		300			μs
Detection delay time						300	μs

2.11 Timing Specifications for Switching Flash Memory Programming Modes

(T_A = –40 to +85°C, 1.8 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Time to complete the communication for the initial setting after the external reset is released	t_{SUINIT}	POR and LVD reset must be released before the external reset is released.			100	ms
Time to release the external reset after the TOOL0 pin is set to the low level	t_{SU}	POR and LVD reset must be released before the external reset is released.	10			μs
Time to hold the TOOL0 pin at the low level after the external reset is released (excluding the processing time of the firmware to control the flash memory)	t_{HD}	POR and LVD reset must be released before the external reset is released.	1			ms



<1> The low level is input to the TOOL0 pin.

<2> The external reset is released (POR and LVD reset must be released before the external reset is released.).

<3> The TOOL0 pin is set to the high level.

<4> Setting of the flash memory programming mode by UART reception and completion the baud rate setting.

Remark t_{SUINIT}: Communication for the initial setting must be completed within 100 ms after the external reset is released during this period.

t_{SU}: Time to release the external reset after the TOOL0 pin is set to the low level

t_{HD}: Time to hold the TOOL0 pin at the low level after the external reset is released (excluding the processing time of the firmware to control the flash memory)

"G: Industrial applications (T_A = –40 to +105°C) differ from "A: Consumer applications" in function as follows:

Fields of Application	A: Consumer applications	G: Industrial applications
Operating ambient temperature	T_A = –40 to +85°C	T_A = –40 to +105°C
Operation mode operating voltage range	HS (high-speed main) mode: 2.7 V ≤ V_{DD} ≤ 5.5 V@1 MHz to 24 MHz 2.4 V ≤ V_{DD} ≤ 5.5 V@1 MHz to 16 MHz LS (low-speed main) mode: 1.8 V ≤ V_{DD} ≤ 5.5 V@1 MHz to 8 MHz LV (low-voltage main) mode: 1.6 V ≤ V_{DD} ≤ 5.5 V@1 MHz to 4 MHz	HS (high-speed main) mode only: 2.7 V ≤ V_{DD} ≤ 5.5 V@1 MHz to 24 MHz 2.4 V ≤ V_{DD} ≤ 5.5 V@1 MHz to 16 MHz
High-speed on-chip oscillator clock accuracy	1.8 V ≤ V_{DD} ≤ 5.5 V: ±1.0 % @ T_A = –20 to +85°C ±1.5 % @ T_A = –40 to –20°C 1.6 V ≤ V_{DD} < 1.8 V: ±5.0 % @ T_A = –20 to +85°C ±5.5 % @ T_A = –40 to –20°C	2.4 V ≤ V_{DD} ≤ 5.5 V: ±2.0 % @ T_A = +85 to +105°C ±1.0 % @ T_A = –20 to +85°C ±1.5 % @ T_A = –40 to –20°C
Serial array unit	UART CSI: f_{CLK}/2 (16 Mbps supported), f_{CLK}/4 Simplified I^2C	UART CSI: f_{CLK}/4 Simplified I^2C
IICA	Standard mode Fast mode Fast mode plus	Standard mode Fase mode
Voltage detector	• Rising: 1.67 V to 4.06 V (14 levels) • Falling: 1.63 V to 3.98 V (14 levels)	• Rising: 2.61 V to 4.06 V (8 levels) • Falling: 2.55 V to 3.98 V (8 levels)

Remark Electrical specifications of G: Industrial applications (T_A = –40 to +105°C) differ from "A: Consumer applications". For details, see **3.1** to **3.11** below.

3.1 Absolute Maximum Ratings

Absolute Maximum Ratings (1/3)

Parameter	Symbol	Conditions	Ratings	Unit
Supply voltage	V_{DD}		–0.5 to +6.5	V
REGC pin input voltage	V_{IREGC}	REGC	–0.3 to +2.8 and –0.3 to V_{DD} +0.3 Note 1	V
Input voltage	V_{I1}	P00 to P07, P10 to P17, P20 to P27, P30 to P35, P40 to P47, P50 to P57, P60, P61, P70 to P77, P121 to P127, P130, P137	–0.3 to V_{DD} +0.3 Note 2	V
	V_{I2}	P60 and P61 (N-ch open-drain)	–0.3 to +6.5	V
	V_{I3}	EXCLK, EXCLKS, $\overline{\text{RESET}}$	–0.3 to V_{DD} +0.3 Note 2	V
Output voltage	V_{O1}	P00 to P07, P10 to P17, P20 to P27, P30 to P35, P40 to P47, P50 to P57, P60, P61, P70 to P77, P121 to P127, P130, P137	–0.3 to V_{DD} +0.3 Note 2	V
Analog input voltage	V_{AI1}	ANI0, ANI1, ANI16 to ANI26	–0.3 to V_{DD} +0.3 and –0.3 to $AV_{REF(+)}$ +0.3 Notes 2, 3	V

Notes 1. Connect the REGC pin to Vss via a capacitor (0.47 to 1 μF). This value regulates the absolute maximum rating of the REGC pin. Do not use this pin with voltage applied to it.

2. Must be 6.5 V or lower.

3. Do not exceed $AV_{REF(+)}$ + 0.3 V in case of A/D conversion target pin.

Caution Product quality may suffer if the absolute maximum rating is exceeded even momentarily for any parameter. That is, the absolute maximum ratings are rated values at which the product is on the verge of suffering physical damage, and therefore the product must be used under conditions that ensure that the absolute maximum ratings are not exceeded.

Remarks 1. Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.

2. $AV_{REF(+)}$: + side reference voltage of the A/D converter.

3. V_{SS}: Reference voltage

Notes 1. Total current flowing into V_{DD}, including the input leakage current flowing when the level of the input pin is fixed to V_{DD} or V_{SS}. The values below the MAX. column include the peripheral operation current. However, not including the current flowing into the LCD controller/driver, A/D converter, LVD circuit, comparator, I/O port, on-chip pull-up/pull-down resistors, and the current flowing during data flash rewrite.

2. When high-speed on-chip oscillator and subsystem clock are stopped.

3. When high-speed system clock and subsystem clock are stopped.

4. When high-speed on-chip oscillator and high-speed system clock are stopped. When setting ultra-low power consumption oscillation (AMPHS1 = 1). The current flowing into the LCD controller/driver, 16-bit timer KB20, real-time clock 2, 12-bit interval timer, and watchdog timer is not included.

5. Relationship between operation voltage width, operation frequency of CPU and operation mode is as below.

HS (high-speed main) mode: 2.7 V ≤ V_{DD} ≤ 5.5 V@1 MHz to 24 MHz

2.4 V ≤ V_{DD} ≤ 5.5 V@1 MHz to 16 MHz

Remarks 1. f_{MX}: High-speed system clock frequency (X1 clock oscillation frequency or external main system clock frequency)

2. f_{HOCO}: High-speed on-chip oscillator clock frequency (48 MHz max.)

3. f_{IH}: High-speed on-chip oscillator clock frequency (24 MHz max.)

4. f_{SUB}: Subsystem clock frequency (XT1 clock oscillation frequency)

5. Except subsystem clock operation, temperature condition of the TYP. value is T_A = 25°C

Notes 1. Excludes quantization error (±1/2 LSB).

2. This value is indicated as a ratio (%FSR) to the full-scale value.

3. When $AV_{REFP} < V_{DD}$, the MAX. values are as follows.

Overall error: Add ±4 LSB to the MAX. value when $AV_{REFP} = V_{DD}$.

Zero-scale error/Full-scale error: Add ±0.2%FSR to the MAX. value when $AV_{REFP} = V_{DD}$.

Integral linearity error/ Differential linearity error: Add ±2 LSB to the MAX. value when $AV_{REFP} = V_{DD}$.

4. See **3.6.2 Temperature sensor/internal reference voltage characteristics**.

(2) When reference voltage (+) = V_{DD} (ADREFP1 = 0, ADREFP0 = 0), reference voltage (–) = V_{SS} (ADREFM = 0), target pins: ANI0, ANI1, ANI16 to ANI25, internal reference voltage, and temperature sensor output voltage

(T_A = –40 to +105°C, 2.4 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V, Reference voltage (+) = V_{DD}, Reference voltage (–) = V_{SS})

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Resolution	RES			8		10	bit
Overall error[Note 1]	AINL	10-bit resolution	2.4 V ≤ V_{DD} ≤ 5.5 V		1.2	±7.0	LSB
Conversion time	t_{CONV}	10-bit resolution Target pin: ANI0, ANI1, ANI16 to ANI25	3.6 V ≤ V_{DD} ≤ 5.5 V	2.125		39	μs
			2.7 V ≤ V_{DD} ≤ 5.5 V	3.1875		39	μs
			2.4 V ≤ V_{DD} ≤ 5.5 V	17		39	μs
		10-bit resolution Target pin: Internal reference voltage, and temperature sensor output voltage (HS (high-speed main) mode)	3.6 V ≤ V_{DD} ≤ 5.5 V	2.375		39	μs
			2.7 V ≤ V_{DD} ≤ 5.5 V	3.5625		39	μs
			2.4 V ≤ V_{DD} ≤ 5.5 V	17		39	μs
Zero-scale error[Notes 1, 2]	E_{ZS}	10-bit resolution	2.4 V ≤ V_{DD} ≤ 5.5 V			±0.60	%FSR
Full-scale error[Notes 1, 2]	E_{FS}	10-bit resolution	2.4 V ≤ V_{DD} ≤ 5.5 V			±0.60	%FSR
Integral linearity error[Note 1]	ILE	10-bit resolution	2.4 V ≤ V_{DD} ≤ 5.5 V			±4.0	LSB
Differential linearity error[Note 1]	DLE	10-bit resolution	2.4 V ≤ V_{DD} ≤ 5.5 V			±2.0	LSB
Analog input voltage	V_{AIN}	ANI0, ANI1, ANI16 to ANI25		0		V_{DD}	V
		Internal reference voltage (2.4 V ≤ V_{DD} ≤ 5.5 V, HS (high-speed main) mode))		V_{BGR}[Note 3]			V
		Temperature sensor output voltage (2.4 V ≤ V_{DD} ≤ 5.5 V, HS (high-speed main) mode))		V_{TMPS25}[Note 3]			V

Notes 1. Excludes quantization error (±1/2 LSB).

2. This value is indicated as a ratio (%FSR) to the full-scale value.

3. See **3.6.2 Temperature sensor/internal reference voltage characteristics**.

3.6.3 Comparator

(T_A = –40 to +105°C, 2.4 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Input voltage range	Ivref			0		V_{DD} – 1.4	V
	Ivcmp			–0.3		V_{DD} + 0.3	V
Output delay	td	V_{DD} = 3.0 V Input slew rate > 50 mV/μs	Comparator high-speed mode, standard mode			1.2	μs
			Comparator high-speed mode, window mode			2.0	μs
			Comparator low-speed mode, standard mode		3.0	5.0	μs
High-electric-potential reference voltage	VTW+	Comparator high-speed mode, window mode		0.66V_{DD}	0.76V_{DD}	0.86V_{DD}	V
Low-electric-potential reference voltage	VTW–	Comparator high-speed mode, window mode		0.14V_{DD}	0.24V_{DD}	0.34V_{DD}	V
Operation stabilization wait time	t_{CMP}			100			μs
Internal reference output voltage[Note]	V_{BGR}	2.4 V ≤ V_{DD} ≤ 5.5 V, HS (high-speed main) mode		1.38	1.45	1.50	V

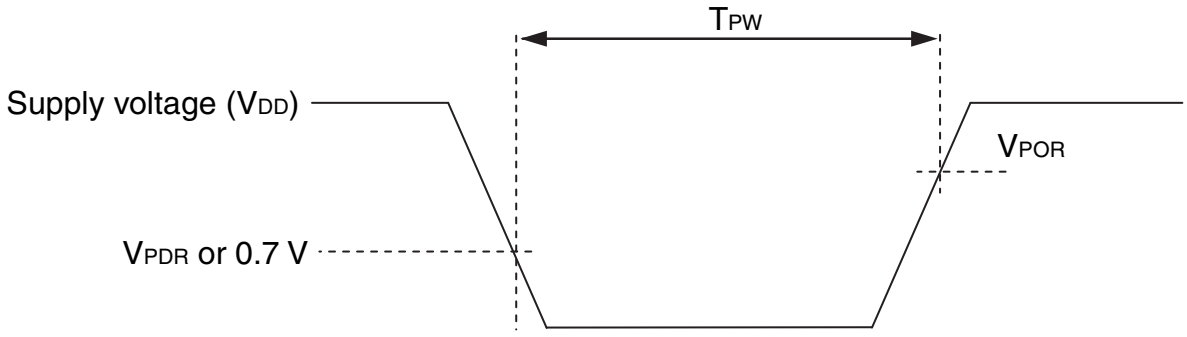
Note Cannot be used in subsystem clock operation and STOP mode.

3.6.4 POR circuit characteristics

(T_A = –40 to +105°C, V_{SS} = 0 V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Detection voltage	V_{POR}	When power supply rises	1.45	1.51	1.57	V
	V_{PDR}	When power supply falls	1.44	1.50	1.56	V
Minimum pulse width[Note]	T_{PW}		300			μs

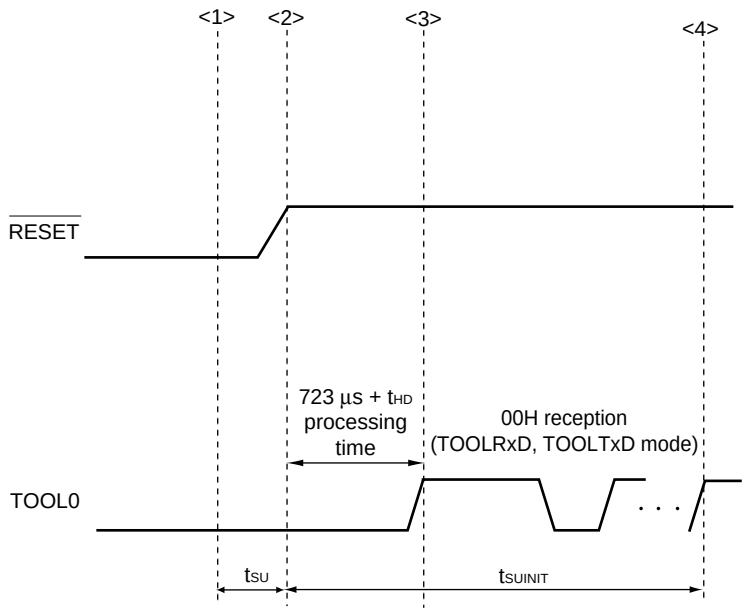
Note This is the time required for the POR circuit to execute a reset operation when V_{DD} falls below V_{PDR}. When the microcontroller enters STOP mode and when the main system clock (f_{MAIN}) has been stopped by setting bit 0 (HIOSTOP) and bit 7 (MSTOP) of the clock operation status control register (CSC), this is the time required for the POR circuit to execute a reset operation between when V_{DD} falls below 0.7 V and when V_{DD} rises to V_{POR} or higher.



3.11 Timing Specifications for Switching Flash Memory Programming Modes

(T_A = –40 to +105°C, 2.4 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Time to complete the communication for the initial setting after the external reset is released	t_{SUINIT}	POR and LVD reset must be released before the external reset is released.			100	ms
Time to release the external reset after the TOOL0 pin is set to the low level	t_{SU}	POR and LVD reset must be released before the external reset is released.	10			μs
Time to hold the TOOL0 pin at the low level after the external reset is released (excluding the processing time of the firmware to control the flash memory)	t_{HD}	POR and LVD reset must be released before the external reset is released.	1			ms



<1> The low level is input to the TOOL0 pin.

<2> The external reset is released (POR and LVD reset must be released before the external reset is released.).

<3> The TOOL0 pin is set to the high level.

<4> Setting of the flash memory programming mode by UART reception and completion the baud rate setting.

Remark t_{SUINIT}: Communication for the initial setting must be completed within 100 ms after the external reset is released during this period.

t_{SU}: Time to release the external reset after the TOOL0 pin is set to the low level

t_{HD}: Time to hold the TOOL0 pin at the low level after the external reset is released (excluding the processing time of the firmware to control the flash memory)